

Spring Meeting 2016

2016 Spring Meeting, Lille May 2-6

Annealing of heavily boron-doped silicon: effect on electric and thermoelectric properties

From May 2nd to 6th Lille Grand Palais - France

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Introduction

- Silicon as thermoelectric material
- State of the art

Experimental work

- Seebeck measurements
- Hall measurements

<u>Results</u>

- Thermal treatments effect
- Transport properties: the two mechanism model

Conclusions and perspectives



SILICON AS THERMOELECTRIC MATERIAL

• Great abundance

- Low cost
- Huge know how of producion and manipulation

Poor thermoelectric performances Si figure of merit ZT≈0.01

$$ZT = \frac{S^2 \sigma}{k_e + k_{ph}} T$$

Increasing power factor $S^2\sigma$ through energy filtering







Seebeck coefficient can be increased eliminating low-energy carriers

N. Neophytou, et al; Journal of Electronic Materials **43**, 1896-1094 (2014)

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STATE OF THE ABT

PolySi thin film (450-200 nm)



B. Lorenzi et al. Journal of ELECTRONIC MATERIALS, Vol. 43, No. 10, 2014

D. Narducci et al. Journal of Solid State Chemistry 193, 19-25, (2012)



Formation of precipitates is evidenced by TEM images





Polycrystalline silicon d=228 nm Doping B 4.4×10^{20} cm⁻³ Annealing in Ar following different protocols

Samples have been submitted to different thermal treatment protocols in order to evaluate the effect of annealing on different TE properties.

Sample	T=900 °C	T=1000 °C	T=1000 °C
AG	-	-	-
TT900(2)	2h	-	-
TT1000(2)	-	2h	-
TT900(2)1000(2)	2h	2h	-
TT1000(2+2)	-	2h	2h
TT1000(4)	-	4h	-



Seebeck sample: 5x50 mm Hall sample: 12x12 mm





SAMPLE	Power Factor (mW/K ² m)
AG	0.95
TT900(2)	4.72
TT1000(2)	9.82
TT900(2)1000(2)	11.31
TT1000(2+2)	13.13
TT1000(4)	4.78



Best result obtained for TT1000(2+2) Duration of TT is not the only crucial parameter to be taken into account!!

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EFFECT OF THERMAL TREATMENTS





EFFECT OF THEBMAL TREATMENTS

After thermal treatments: Hall coefficient $R = \frac{F}{n_c e}$



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CONDUCTION REGIMES











CONDUCTION REGIMES





TWO COMPETING MECHANISM

Impurity semiconductor model (localized energy states)



Different kind of carriers plays a role with different mobility

conduction band carriers:

$$\sigma_{\rm C}, \ \mu_c = c R_c \sigma_c$$

Hopping conduction carrier:

$$\sigma_{\rm h}, \ \mu_h = c R_h \sigma_h$$

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$$\rho = \frac{1}{n_c e \mu_c + n_h e \mu_h}$$
$$R = F \frac{n_c e \mu_c^2 + n_h e \mu_h^2}{(n_c e \mu_c + n_h e \mu_h)^2}$$



HALL COEFFICIENT

$$R_{c.h} = \frac{1}{en_{c,h}} \quad \sigma_{c.h} = n_{c,h}e\mu_{c,h}$$

$$R = \frac{R_c \sigma_c^2 + R_h \sigma_h^2}{\left(\sigma_c + \sigma_h\right)^2}$$



If $\mu_h << \mu_c$

$$R \approx \frac{R_c {\sigma_c}^2}{(\sigma_c + \sigma_h)^2}$$
 We have a maximum for $\sigma_h \approx \sigma_c$

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In the low temperature limit $n_c = 0$ \longrightarrow $R = F \frac{1}{n_h e} \approx \frac{1}{ne}$ (all the carrier are in the impurity band)



We expect the value of R to be the same at low and high temperature

$$R_{LT}^{EXP} = 0.070 \pm 0.002$$
$$R_{HT}^{EXP} = 0.074 \pm 0.002$$



MODEL VS EXPERIMENTAL RATA







✓ Study on the annealing effect on TE performances heavily doped nanocrystalline silicon thin film

✓ Best performances for double thermal treatments at 1000 ℃ (power factor 13.13 mW/ K² m)

✓ The model used for homogeneous system is not longer valid at low temperature

✓ From resistivity measurements we can distinguish between three different conduction regime in temperature

✓ A simply model (two conduction mechanism) reproduces experimental data

✓ Relation between TE performances and transport mechanism is still unknow

✓ Further investigation and ad hoc model are needed!





Thermoelectrics Research Group

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